Stress Free
Reworkable
Electrically Conductive
B-Staged Epoxy Film Adhesive

IDEAL FOR:
- Substrate and Component
- Reworkability
- Mismatched CTE’s

DESCRIPTION:
TC8750 is a silver-filled, B-staged epoxy film adhesive. It is designed for bonding component and substrate to a mismatched substrate or carrier. Its low $T_g$ imposes minimum thermal stress on bonded parts during thermal cycling or shock testing. It has excellent thermal conductivity and can be used for most applications at temperatures from -65 to 150°C. It is reworkable at 80-150°C. Customers must test the adhesive for their specific applications to confirm its suitability.

TC8750 is designed to meet the hybrid adhesive specification MIL-STD-883; Method 5011. It exhibits low outgassing at 125°C and passes NASA outgassing requirements.

APPLICATION PROCEDURES:
(1) Let adhesive thaw in bag or plastic box for 30 min. Cut to desired size.
(2) Lift the corner of a release liner on one side of the tack film. Peel the release liner over to 180° and pull quickly to remove the liner in one stroke. Attach to components, and then peel the 2nd release liner.

***PLEASE NOTE: When this product is removed from the freezer, used and refrozen, the shelf life @ -40°C and pot life @ 25°C is lowered depending on the amount of time out of the -40°C freezer.

CAUTION:
This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to the SDS for more details.

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